

UNITED STATES PATENT AND TRADEMARK OFFICE
CERTIFICATE OF CORRECTION

PATENT NO. : 6,797,591 B1
APPLICATION NO. : 09/661766
DATED : September 28, 2004
INVENTOR(S) : Gormley et al.

Page 1 of 1

It is certified that error appears in the above-identified patent and that said Letters Patent is hereby corrected as shown below:

In Column 10, claim 10, line 64, delete "second stop layer being bonded to the one of the second and" and replace with --second etch stop layer being bonded to the one of the second and--

In Column 11, claim 17, line 18, delete "16" and replace with --15--

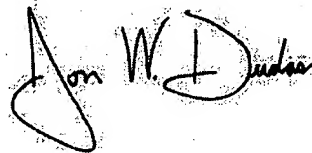
In Column 11, claim 20, line 30, delete " second and third layers and of semiconductor material." and replace with -- second and third layers are of semiconductor material.--

In Column 12, claim 31, line 23, delete the word "each" and insert the word --etch--

In Column 12, claim 38, line 48 , delete "first layer is at least half the area of the component in plan" and insert --first layer adjacent the component is at least half the area of the component in plan--

Signed and Sealed this

Seventeenth Day of April, 2007

A handwritten signature in black ink, appearing to read "Jon W. Dudas", is written over a faint circular embossed seal of the United States Patent and Trademark Office.

JON W. DUDAS
Director of the United States Patent and Trademark Office